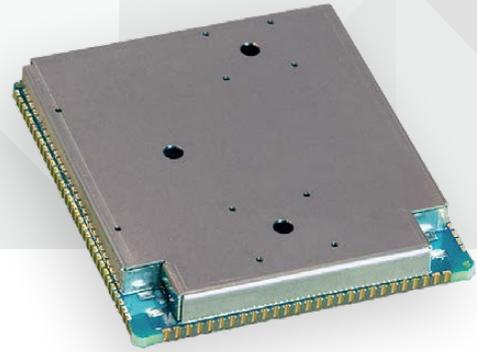




SECURE, CONNECTED
SYSTEM-ON-MODULE



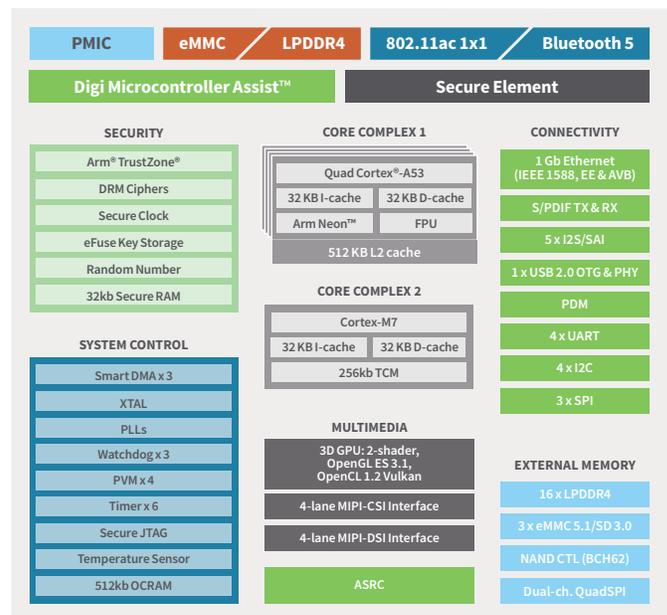
DIGI CONNECTCORE 8M NANO

Embedded system-on-module based on the NXP i.MX 8M Nano processor; designed for longevity and scalability in industrial IoT applications

Digi ConnectCore® 8M Nano, based on the NXP® i.MX 8M Nano application processor, is an integrated system-on-module (SOM) platform. The Nano is designed for a wide range of industrial, medical, agricultural and transportation applications, including Internet of Things (IoT), human-machine interface (HMI), equipment monitoring, audio/voice, edge computing and machine learning (e.g. anomaly detection).

Digi ConnectCore 8M Nano features up to 4x power-efficient Arm® Cortex®-A53 cores and 1x Cortex-M7 core, which allow it to minimize power consumption while maintaining a high standard of performance. This SOM is designed for industrial reliability and the 10+ year product lifecycles of embedded devices. It helps OEMs lower their R&D and development costs and realize a lower total cost of ownership by leveraging pre-certified wireless connectivity, remote management, cloud integration and a complete Linux software platform based on Yocto Project®. In addition, built in Digi TrustFence® enables OEM developers to integrate critical security and data privacy capabilities into their products.

BLOCK DIAGRAM



BENEFITS

- Industrial i.MX 8M Nano quad/dual-core System-on-Module
- Digi SMTplus® form factor (40 mm x 45 mm) for ultimate reliability and design freedom
- Power management with both hardware and software support for low-power designs
- Multi-display and camera capabilities with hardware acceleration
- Pre-certified dual-band 802.11a/b/g/n/ac 1x1 and Bluetooth® 5 connectivity
- Seamless cellular modem and Digi XBee® integration
- Cloud and edge-compute services integration
- Built-in device security, identity and privacy with Digi TrustFence®
- Remote monitoring and management with Digi Remote Manager®
- Yocto Project Linux support

RELATED PRODUCTS



ConnectCore
8M Nano Dev Kit



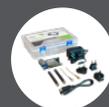
ConnectCore
8X



ConnectCore
6UL



Digi XBee®
Modules



ConnectCore
8X SBC Pro Dev Kit

| SPECIFICATIONS | Digi ConnectCore® 8M Nano |
|---|--|
| APPLICATION PROCESSOR | NXP i.MX8 Nano <ul style="list-style-type: none"> • 4x Cortex-A53 cores @ 1.4 GHz • 1x Cortex-M7 core @ 750 MHz core for real-time processing |
| MEMORY | Up to 8 GB eMMC, up to 1 GB of LPDDR4 (16-bit) |
| PMIC | Rohm BD71850MWV |
| GRAPHICS | Graphic Processing Unit: <ul style="list-style-type: none"> • GC7000UL with OpenCL and Vulkan support • 2 shader • 123 million triangles / sec • 0.8 giga pixel / sec • 12.8 GFLOPs 32-bit / 12.8 GFLOPs 16-bit • Supports OpenGL ES 1.1, 2.0, 3.0, OpenCL • Shader clock frequency of 500 MHz LCDIF display controller, supporting up to 1080p 60fps display through MIPI DSI 4-lane MIPI DSI interface |
| SECURITY | Digi TrustFence®, TRNG, TrustZone, Secure RTC, Secure JTAG, Secure Element |
| PERIPHERALS/ INTERFACES | 1x USB 2.0 OTG controllers with integrated PHY interfaces 3x Ultra Secure Digital Host Controller (uSDHC) interfaces 1x Gigabit Ethernet controller 4x Universal Asynchronous Receiver / Transmitter (UART) modules 4x I2C modules 3x SPI modules |
| ETHERNET | 1x 10/100/1000M Ethernet + AVB |
| WI-FI | 1x1 802.11a/b/g/n/ac dual-band wireless |
| BLUETOOTH | Bluetooth® 5 |
| ON-MODULE MICROCONTROLLER ASSIST | Digi Microcontroller Assist™ <ul style="list-style-type: none"> • Independent Cortex-M0+ microcontroller subsystem • Supporting ultra-low power modes @ <3µA |
| OPERATING TEMPERATURE | Industrial: -40° C to 85° C (-40° F to 185° F), depending on use case and enclosure/system design |
| STORAGE TEMPERATURE | -50° C to 125° C (-58° F to 257° F) |
| RELATIVE HUMIDITY | 5% to 90% (non-condensing) |
| RADIO APPROVALS | US, Canada, EU, Japan, Australia/New Zealand |
| EMISSIONS/ IMMUNITY/ SAFETY | FCC Part 15 Class B, EN 55022 Class B, EN 61000-3-2, EN 61000-3-3, ICES- 003 Class B, VCCI Class II, AS 3548, FCC Part 15 Subpart C Section 15.247, IC (Industry Canada), RSS-210 Issue 5 Section 6.2.2(o), EN 300 328, EN 301 489-17, EN 55024, EN 301 489-3 |
| DESIGN VERIFICATION | Temperature: IEC 60068-2-1, IEC 60068-2-2, IEC 60068-2-78 Vibration/Shock: IEC 60068-2-6, IEC 60068-2-64, IEC 60068-2-27, HALT |
| MECHANICAL DIMENSIONS | 118 castellated vias, LGA-474, 1.27 mm pitch, fully shielded for radio emissions and thermal management (heat-spreading) 40 mm x 45 mm x 3.5 mm (1.6 in x 1.8 in x 0.1 in) |
| PRODUCT WARRANTY | 3-year |

| PART NUMBERS | DESCRIPTION |
|--|---|
| DIGI CONNECTCORE 8M NANO DEVELOPMENT KITS | |
| CC-WMX8MN-KIT | Digi ConnectCore 8M Nano development kit with development board, Quad Core, 8 GB eMMC, 1 GB LPDDR4 Wireless |
| DIGI CONNECTCORE 8M NANO SOMS | |
| CC-WMX-FS7D-NN | Digi ConnectCore 8M Nano, Quad Core, 8 GB eMMC, 1 GB LPDDR4 Wireless |
| CC-WMX-FR6D-NN | Digi ConnectCore 8M Nano, SoloLite Core, 8 GB eMMC, 512 MB LPDDR4 Wireless |
| CC-MX-FS7D-ZN | Digi ConnectCore 8M Nano, Quad Core, 8 GB eMMC, 1 GB LPDDR4 Ethernet |
| CC-MX-FR6D-ZN | Digi ConnectCore 8M Nano, SoloLite Core, 8 GB eMMC, 512 MB LPDDR4 Ethernet |

| ACCESSORIES | DESCRIPTION |
|----------------|--|
| CC-ACC-LCDW-10 | LCD application kit, including 10 in WXGA (1280x800) LCD panel with PCAP touch |

FOR MORE INFORMATION
PLEASE VISIT DIGI.COM



The information provided in this document is preliminary and may be subject to change without notice.

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